



APPLICATIONS

- Battery-powered devices
- IoT
- Wearable
- Portable devices
- Input filters

FEATURES

- Size 2mmx2.5mmx1.2mm
- Semi-Shielded Construction
- Low DCR
- Low Profile
- Low Stray Field
- Max Operating Temp +125°C
- RoHS/REACH-Compliant, Halogen-Free

ELECTRICAL CHARACTERISTICS

Parameter			Value	Unit
Inductance ⁽¹⁾	L	$\pm 20\%$	2.2	μ H
Resistance	R_{DC}	typ	92	m Ω
Resistance _{MAX}	$R_{DC\ MAX}$	max	118	m Ω
Rated Current ⁽²⁾	I_R	typ	2.5	A
Saturation Current _{25°C} ⁽³⁾	$I_{SAT\ 25°C}$	typ	2.7	A
Saturation Current _{100°C} ⁽⁴⁾	$I_{SAT\ 100°C}$	typ	2.7	A
Resonance Frequency	f_r	typ	56	MHz

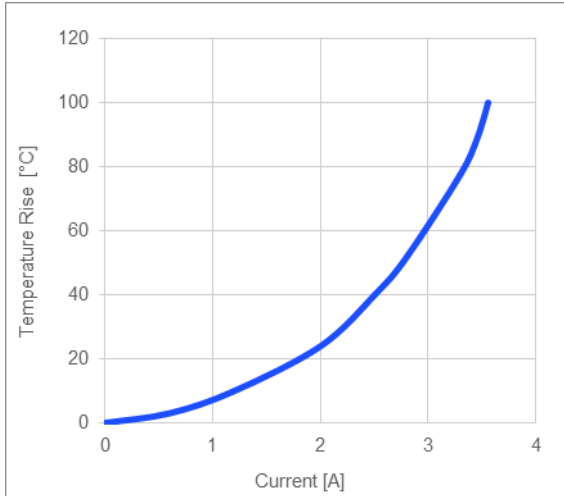
GENERAL SPECIFICATIONS

⁽¹⁾ Inductance	Measured at 100kHz, 100mA
⁽²⁾ Rated Current	Rated current will cause the coil temperature rise ΔT of 40K I_R measured with the inductor soldered in a single-layer PCB. Copper layer thickness 35 μ m Cu / PCB size 30x50mm. Temperature behavior dependent on circuit design, PCB layout, proximity to other components, and trace dimensions and thickness.
⁽³⁾ Saturation Current _{25°C}	Saturation current will cause L to drop from 30% at 25°C ambient temperature
⁽⁴⁾ Saturation Current _{100°C}	Saturation current will cause L to drop from 30% at 100°C ambient temperature
Temperature Test Condition	Electrical specifications measured at 25°C, 35% RH if not given differently
Operating Condition	Operating temperature: -40°C to +125°C (including temp rise) Should not exceed +125°C under worst-case operation conditions
Storage Condition	Tape and Reel packaging: -10°C to +40°C Humidity: <50% RH

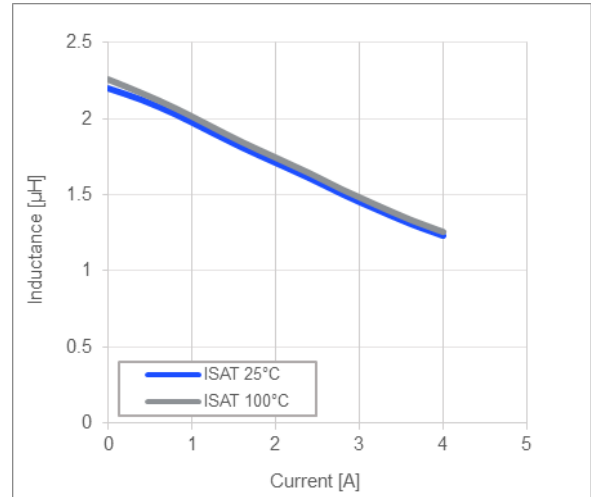
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TYPICAL PERFORMANCE CURVES

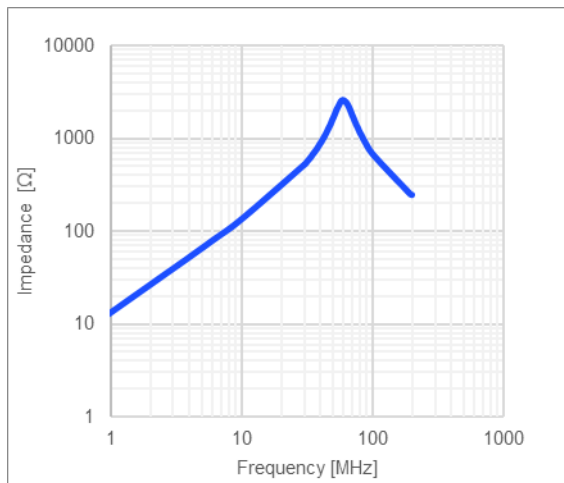
Temperature Rise vs. Current



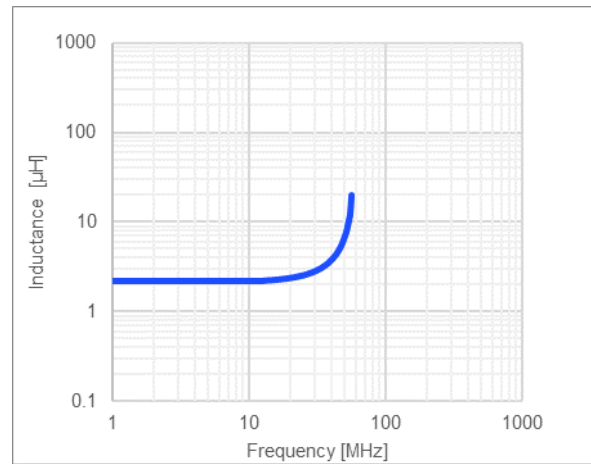
Inductance vs. Current



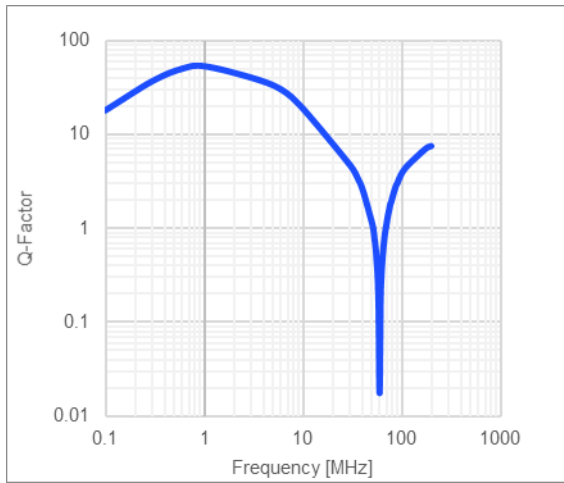
Impedance vs. Frequency



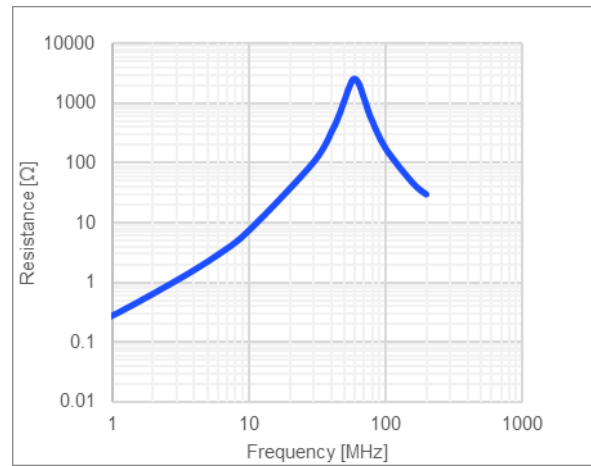
Inductance vs. Frequency



Quality Factor vs. Frequency



AC Resistance vs. Frequency



LAND PATTERN

Dimensions

A	2.10 ref.
B	0.80 ref.
C	2.60 ref.

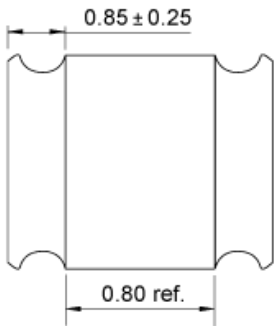
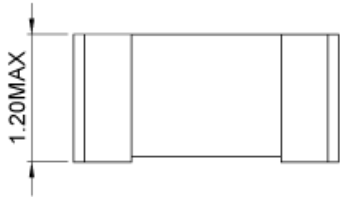
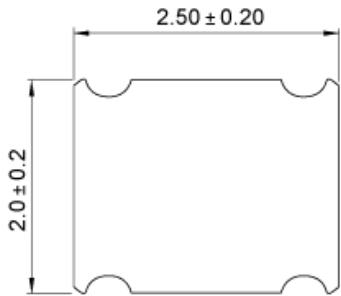
(unit in mm)



PRODUCT PACKAGE AND DIMENSIONS

Dimensions

(unit in mm)



ORDERING INFORMATION

Part Number	$L^{(1)}$	R_{DC}	$I_R^{(2)}$	$I_{SAT\ 25^{\circ}C}^{(3)}$	$I_{SAT\ 100^{\circ}C}^{(4)}$
	typ (μH)	typ (mΩ)	typ (A)	typ (A)	typ (A)
MPL-SE2512-R47	0.47	27	4.5	6.5	6.5
MPL-SE2512-R68	0.68	33	3.8	4.3	4.3
MPL-SE2512-1R0	1.0	45	3.35	4.2	4.2
MPL-SE2512-1R5	1.5	62	2.9	3.2	3.2
MPL-SE2512-2R2	2.2	92	2.5	2.7	2.7
MPL-SE2512-3R3	3.3	158	1.8	2.4	2.4
MPL-SE2512-4R7	4.7	205	1.6	1.9	1.9
MPL-SE2512-100	10	400	1.1	1.3	1.3
MPL-SE2512-150	15	620	0.85	0.9	0.9
MPL-SE2512-220	22	1000	0.70	0.8	0.8

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